Renesas Electronics America Inc - R5F2121CJFP#U0 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, Voltage Detect, WDT
Number of I/O	41
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2121cjfp-u0

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1.4 Product Information

Table 1.3 lists Product Information for R8C/20 Group and Table 1.4 lists Product Information for R8C/21 Group.

Table 1.3 Product Information for R8C/20 Group **Current of Aug. 2008**

Type No.	ROM Capacity	RAM Capacity	Package Type	Remarks	
R5F21206JFP	32 Kbytes	2 Kbytes	PLQP0048KB-A	J version	Flash memory version
R5F21207JFP	48 Kbytes	2.5 Kbytes	PLQP0048KB-A		
R5F21208JFP	64 Kbytes	3 Kbytes	PLQP0048KB-A		
R5F2120AJFP	96 Kbytes	5 Kbytes	PLQP0048KB-A		
R5F2120CJFP	128 Kbytes(1)	6 Kbytes	PLQP0048KB-A		
R5F21206KFP	32 Kbytes	2 Kbytes	PLQP0048KB-A	K version	
R5F21207KFP	48 Kbytes	2.5 Kbytes	PLQP0048KB-A		
R5F21208KFP	64 Kbytes	3 Kbytes	PLQP0048KB-A		
R5F2120AKFP	96 Kbytes	5 Kbytes	PLQP0048KB-A		
R5F2120CKFP	128 Kbytes(1)	6 Kbytes	PLQP0048KB-A		

NOTE:
1. Do not use addresses 20000h to 23FFFh because these areas are used for the emulator debugger. Refer to **23. Notes on Emulator Debugger** of Hardware Manual.

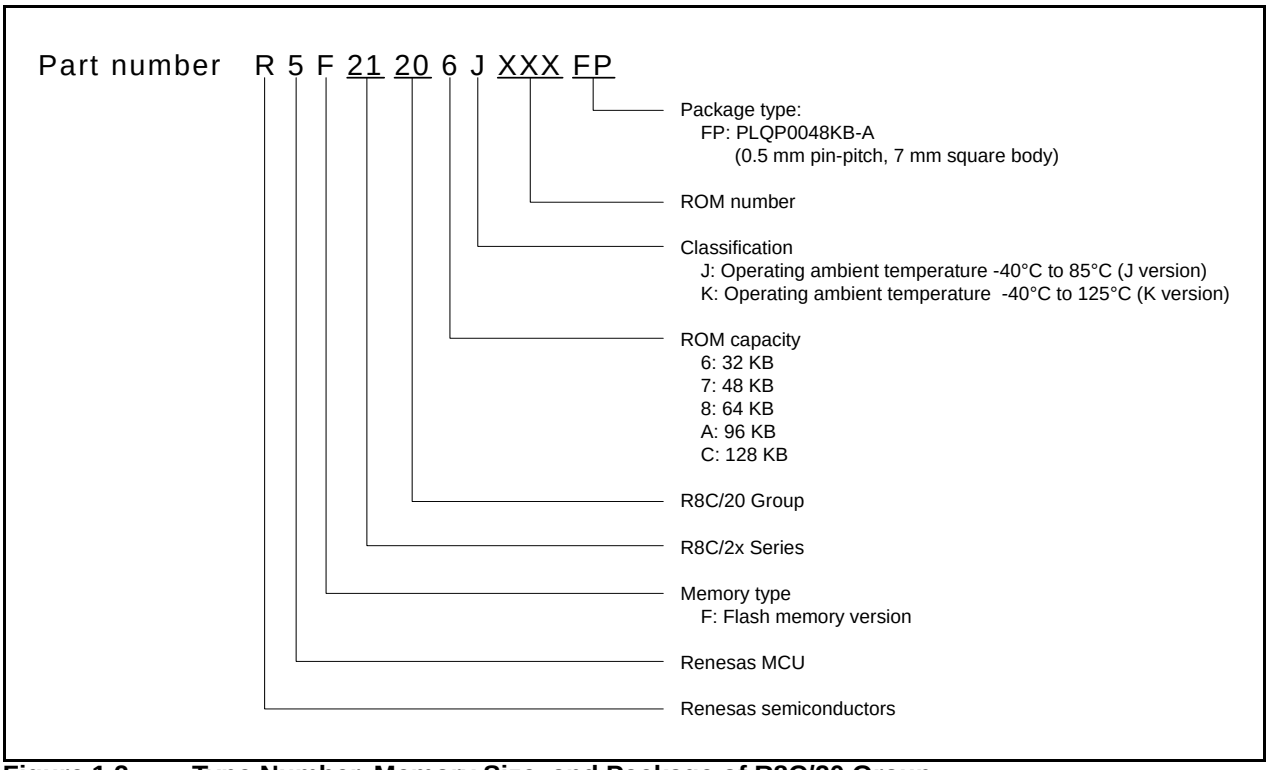


Figure 1.2 Type Number, Memory Size, and Package of R8C/20 Group

1.6 Pin Functions

Table 1.5 lists the Pin Functions and Table 1.6 lists the Pin Name Information by Pin Number.

Table 1.5 Pin Functions

Type	Symbol	I/O Type	Description
Power Supply Input	VCC VSS	I	Apply 2.7 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog Power Supply Input	AVCC, AVSS	I	Applies the power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset Input	$\overline{\text{RESET}}$	I	Input “L” on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN Clock Input	XIN	I	These pins are provided for the XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins. To use an externally derived clock, input it to the XIN pin and leave the XOUT pin open.
XIN Clock Output	XOUT	O	
$\overline{\text{INT}}$ Interrupt Input	$\overline{\text{INT0}}$ to $\overline{\text{INT3}}$	I	$\overline{\text{INT}}$ interrupt input pins. $\overline{\text{INT0}}$ Timer RD input pins. $\overline{\text{INT1}}$ Timer RA input pins.
Key Input Interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input pins.
Timer RA	TRAIO	I/O	Timer RA I/O pin.
	TRAO	O	Timer RA output pin.
Timer RB	TRBO	O	Timer RB output pin.
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O ports.
	TRDCLK	I	External clock input pin.
Timer RE	TREO	O	Divided clock output pin.
Serial Interface	CLK0	I/O	Transfer clock I/O pin.
	RXD0, RXD1	I	Serial data input pins.
	TXD0, TXD1	O	Serial data output pins.
I^2C Bus Interface	SCL	I/O	Clock I/O pin.
	SDA	I/O	Data I/O pin.
Clock Synchronous Serial I/O with Chip Select	SSI	I/O	Data I/O pin.
	$\overline{\text{SCS}}$	I/O	Chip-select signal I/O pin.
	SSCK	I/O	Clock I/O pin.
	SSO	I/O	Data I/O pin.
Reference Voltage Input	VREF	I	Reference voltage input pin to A/D converter.
A/D Converter	AN0 to AN11	I	Analog input pins to A/D converter.
I/O Port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_5, P6_0 to P6_7	I/O	CMOS I/O ports. Each port contains an input/output select direction register, allowing each pin in that port to be directed for input or output individually. Any port set to input can select whether to use a pull-up resistor or not by a program.
Input Port	P4_2, P4_6, P4_7	I	Input only ports.

I: Input O: Output I/O: Input and output

2.1 Data Registers (R0, R1, R2 and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3.
R0 can be split into high-order bit (R0H) and low-order bit (R0L) to be used separately as 8-bit data registers. The same applies to R1H and R1L as R0H and R0L. R2 can be combined with R0 to be used as a 32-bit data register (R2R0). The same applies R3R1 as R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. They also are used for transfer, arithmetic and logic operations. The same applies to A1 as A0.
A1 can be combined with A0 to be used a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB, a 20-bit register, indicates the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC, 20 bits wide, indicates the address of an instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointer (SP), USP and ISP, are 16 bits wide each.
The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is a 11-bit register indicating the CPU status.

2.8.1 Carry Flag (C)

The C flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debug only. Set to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation resulted in 0; otherwise, 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation resulted in a negative value; otherwise, 0.

2.8.5 Register Bank Select Flag (B)

The register bank 0 is selected when the B flag is 0. The register bank 1 is selected when this flag is set to 1.

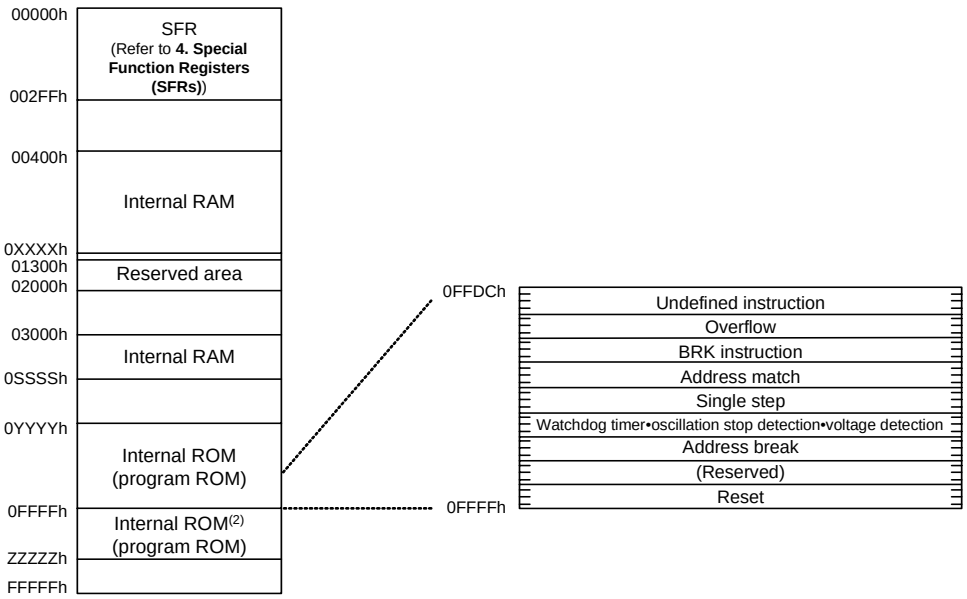
2.8.6 Overflow Flag (O)

The O flag is set to 1 when the operation resulted in an overflow; otherwise, 0.

3. Memory

3.1 R8C/20 Group

Figure 3.1 shows a Memory Map of R8C/20 Group. The R8C/20 Group has 1 Mbyte of address space from address 00000h to FFFFFh.
The internal ROM is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM is allocated addresses 04000h to 0FFFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.
The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.
Special function registers (SFR) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future user and cannot be accessed by users.



NOTES:
1. The blank regions are reserved. Do not access locations in these regions.
2. Do not use addresses 20000h to 23FFFh because these areas are used for the emulator debugger. Refer to **23. Notes on Emulator Debugger** of Hardware Manual.

Part Number	Internal ROM			Internal RAM		
	Size	Address 0YYYYh	Address ZZZZZh	Size	Address 0XXXXh	Address 0SSSSh
R5F21206JFP, R5F21206KFP	32 Kbytes	08000h	-	2 Kbytes	00BFFh	-
R5F21207JFP, R5F21207KFP	48 Kbytes	04000h	-	2.5 Kbytes	00DFFh	-
R5F21208JFP, R5F21208KFP	64 Kbytes	04000h	13FFFh	3 Kbytes	00FFFh	-
R5F2120AJFP, R5F2120AKFP	96 Kbytes	04000h	1BFFFh	5 Kbytes	00FFFh	037FFh
R5F2120CJFP, R5F2120CKFP	128 Kbytes	04000h	23FFFh	6 Kbytes	00FFFh	03BFFh

Figure 3.1 Memory Map of R8C/20 Group

Table 4.2 SFR Information (2)(1)

Address	Register	Symbol	After reset
0040h			
0041h			
0042h			
0043h			
0044h			
0045h			
0046h			
0047h			
0048h	Timer RD0 Interrupt Control Register	TRD0IC	XXXXX000b
0049h	Timer RD1 Interrupt Control Register	TRD1IC	XXXXX000b
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh			
004Ch			
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU Interrupt Control Register/IIC Bus Interrupt Control Register(2)	SSUIC/IICIC	XXXXX000b
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h	INT2 Interrupt Control Register	INT2IC	XX00X000b
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh			
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h			
0073h			
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Selected by the IICSEL bit in the PMR register.

Table 4.4 SFR Information (4)(1)

Address	Register	Symbol	After reset
00C0h	A/D Register	AD	XXh
00C1h			XXh
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Control Register 2	ADCON2	00h
00D5h			
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h	UART1 Function Select Register	U1SR	XXh
00F6h			
00F7h			
00F8h	Port Mode Register	PMR	00h
00F9h	External Input Enable Register	INTEN	00h
00FAh	INT Input Filter Select Register	INTF	00h
00FBh	Key Input Enable Register	KIEN	00h
00FCh	Pull-Up Control Register 0	PUR0	00h
00FDh	Pull-Up Control Register 1	PUR1	XX00XX00b
00FEh			
00FFh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.6 SFR Information (6)(1)

Address	Register	Symbol	After reset
0140h	Timer RD Control Register 0	TRDCR0	00h
0141h	Timer RD I/O Control Register A0	TRDIORA0	10001000b
0142h	Timer RD I/O Control Register C0	TRDIORC0	10001000b
0143h	Timer RD Status Register 0	TRDSR0	11100000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIORA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h			FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh			FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh			FFh
01B0h			
01B1h			
01B2h			
01B3h	Flash Memory Control Register 4	FMR4	01000000b
01B4h			
01B5h	Flash Memory Control Register 1	FMR1	1000000Xb
01B6h			
01B7h	Flash Memory Control Register 0	FMR0	00000001b
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			
FFFFh	Option Function Select Register	OFS	(Note 2)

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. The OFS register cannot be changed by a program. Use a flash programmer to write to it.

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated value	Unit
V_{CC}/AV_{CC}	Supply voltage		-0.3 to 6.5	V
V_I	Input voltage		-0.3 to V_{CC}+0.3	V
V_O	Output voltage		-0.3 to V_{CC}+0.3	V
P_d	Power dissipation	-40°C ≤ Topr ≤ 85°C	300	mW
		85°C < Topr ≤ 125°C	125	mW
T_{opr}	Operating ambient temperature		-40 to 85 (J version) / -40 to 125 (K version)	°C
T_{stg}	Storage temperature		-65 to 150	°C

Table 5.2 Recommended Operating Conditions

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
V_{CC}/AV_{CC}	Supply voltage			2.7	–	5.5	V
V_{SS}/AV_{CC}	Supply voltage			–	0	–	V
V_{IH}	Input “H” voltage			0.8V_{CC}	–	V_{CC}	V
V_{IL}	Input “L” voltage			0	–	0.2V_{CC}	V
$I_{OH(sum)}$	Peak sum output “H” current	Sum of all Pins $I_{OH\ (peak)}$		–	–	-60	mA
$I_{OH(peak)}$	Peak output “H” current			–	–	-10	mA
$I_{OH(avg)}$	Average output “H” current			–	–	-5	mA
$I_{OL(sum)}$	Peak sum output “L” currents	Sum of all Pins $I_{OL\ (peak)}$		–	–	60	mA
$I_{OL(peak)}$	Peak output “L” currents			–	–	10	mA
$I_{OL(avg)}$	Average output “L” current			–	–	5	mA
$f_{(XIN)}$	XIN clock input oscillation frequency		3.0 V ≤ V_{CC} ≤ 5.5 V -40°C ≤ Topr ≤ 85°C	0	–	20	MHz
			3.0 V ≤ V_{CC} ≤ 5.5 V -40°C ≤ Topr ≤ 125°C	0	–	16	MHz
			2.7 V ≤ V_{CC} < 3.0 V	0	–	10	MHz
–	System clock	OCD2 = 0 When XIN clock is selected.	3.0 V ≤ V_{CC} ≤ 5.5 V -40°C ≤ Topr ≤ 85°C	0	–	20	MHz
			3.0 V ≤ V_{CC} ≤ 5.5 V -40°C ≤ Topr ≤ 125°C	0	–	16	MHz
			2.7 V ≤ V_{CC} < 3.0 V	0	–	10	MHz
		OCD2 = 1 When on-chip oscillator clock is selected.	FRA01 = 0 When low-speed on-chip oscillator clock is selected.	–	125	–	kHz
			FRA01 = 1 When high-speed on-chip oscillator clock is selected. 3.0 V ≤ V_{CC} ≤ 5.5 V -40°C ≤ Topr ≤ 85°C	–	–	20	MHz
			FRA01 = 1 When high-speed on-chip oscillator clock is selected.	–	–	10	MHz

NOTES:
1. V_{CC} = 2.7 to 5.5 V at Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.
2. The average output current indicates the average value of current measured during 100 ms.

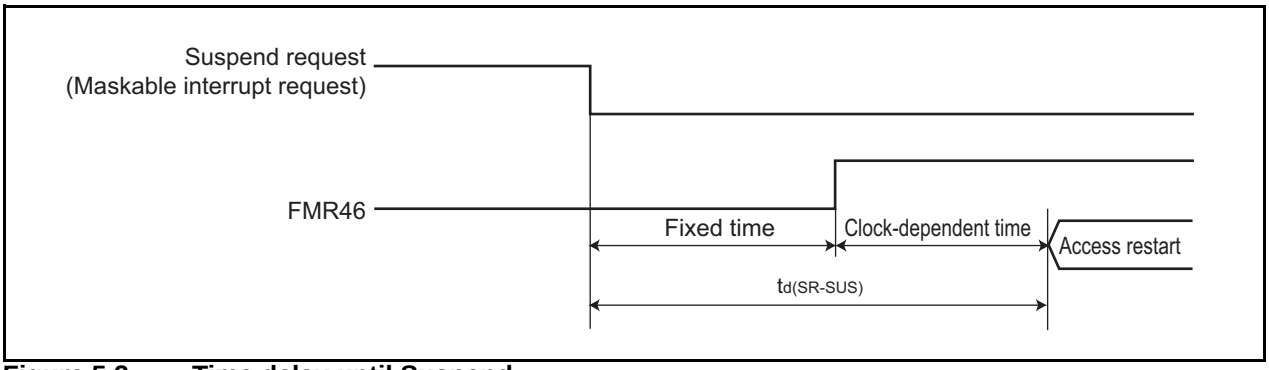


Figure 5.2 Time delay until Suspend

Table 5.6 Voltage Detection 1 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det1}	Voltage detection level(3, 4)		2.70	2.85	3.00	V
$t_{d(Vdet1-A)}$	Voltage monitor 1 reset generation time(5)		–	40	200	µs
–	Voltage detection circuit self power consumption	VCA26 = 1, V_{CC} = 5.0 V	–	0.6	–	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts(2)		–	–	100	µs
Vccmin	MCU operating voltage minimum value		2.70	–	–	V

NOTES:
1. The measurement condition is V_{CC} = 2.7 V to 5.5 V and Topr = -40°C to 85°C (J version) / -40°C to 125°C (K version).
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.
3. Hold $V_{det2} > V_{det1}$.
4. This parameter shows the voltage detection level when the power supply drops. The voltage detection level when the power supply rises is higher than the voltage detection level when the power supply drops by approximately 0.1 V.
5. Time until the voltage monitor 1 reset is generated after the voltage passes V_{det1} when V_{CC} falls. When using the digital filter, its sampling time is added to $t_{d(Vdet1-A)}$. When using the voltage monitor 1 reset, maintain this time until V_{CC} = 2.0 V after the voltage passes V_{det1} when the power supply falls.

Table 5.7 Voltage Detection 2 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det2}	Voltage detection level(4)		3.3	3.6	3.9	V
$t_{d(Vdet2-A)}$	Voltage monitor 2 reset/interrupt request generation time(2, 5)		–	40	200	µs
–	Voltage detection circuit self power consumption	VCA27 = 1, V_{CC} = 5.0V	–	0.6	–	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts(3)		–	–	100	µs

NOTES:
1. The measurement condition is V_{CC} = 2.7 V to 5.5 V and Topr = -40°C to 85°C (J version) / -40°C to 125°C (K version).
2. Time until the voltage monitor 2 reset/interrupt request is generated since the voltage passes V_{det2}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.
4. Hold $V_{det2} > V_{det1}$.
5. When using the digital filter, its sampling time is added to $t_{d(Vdet2-A)}$. When using the voltage monitor 2 reset, maintain this time until V_{CC} = 2.0 V after the voltage passes V_{det2} when the power supply falls.

Table 5.9 High-Speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO40M	High-speed on-chip oscillator frequency temperature • supply voltage dependence	V_{CC} = 4.75 V to 5.25 V, 0°C ≤ Topr ≤ 60°C(2)	39.2	40	40.8	MHz
		V_{CC} = 3.0 V to 5.25 V, -20°C ≤ Topr ≤ 85°C(2)	38.8	40	41.2	MHz
		V_{CC} = 3.0 V to 5.5 V, -40°C ≤ Topr ≤ 85°C(2)	38.4	40	41.6	MHz
		V_{CC} = 3.0 V to 5.5 V, -40°C ≤ Topr ≤ 125°C(2)	38.0	40	42.0	MHz
		V_{CC} = 2.7 V to 5.5 V, -40°C ≤ Topr ≤ 125°C(2)	37.6	40	42.4	MHz
–	The value of the FRA1 register when the reset is deasserted		08h	40	F7h	–
–	High-speed on-chip oscillator adjustment range	Adjust the FRA1 register to -1 bit (the value when the reset is deasserted)	–	+ 0.3	–	MHz
–	Oscillation stability time		–	10	100	µs
–	Self power consumption when high-speed on-chip oscillator oscillating	V_{CC} = 5.0 V, Topr = 25°C	–	600	–	µA

NOTES:
1. V_{CC} = 2.7 V to 5.5 V, Topr = -40°C to 85°C (J version) / -40°C to 125°C (K version), unless otherwise specified.
2. The standard value shows when the reset is deasserted for the FRA1 register.

Table 5.10 Low-Speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		40	125	250	kHz
–	Oscillation stability time		–	10	100	µs
–	Self power consumption when low-speed on-chip oscillator oscillating	V_{CC} = 5.0 V, Topr = 25°C	–	15	–	µA

NOTE:
1. V_{CC} = 2.7 V to 5.5 V, Topr = -40°C to 85°C (J version) / -40°C to 125°C (K version), unless otherwise specified.

Table 5.11 Power Supply Circuit Timing Characteristics

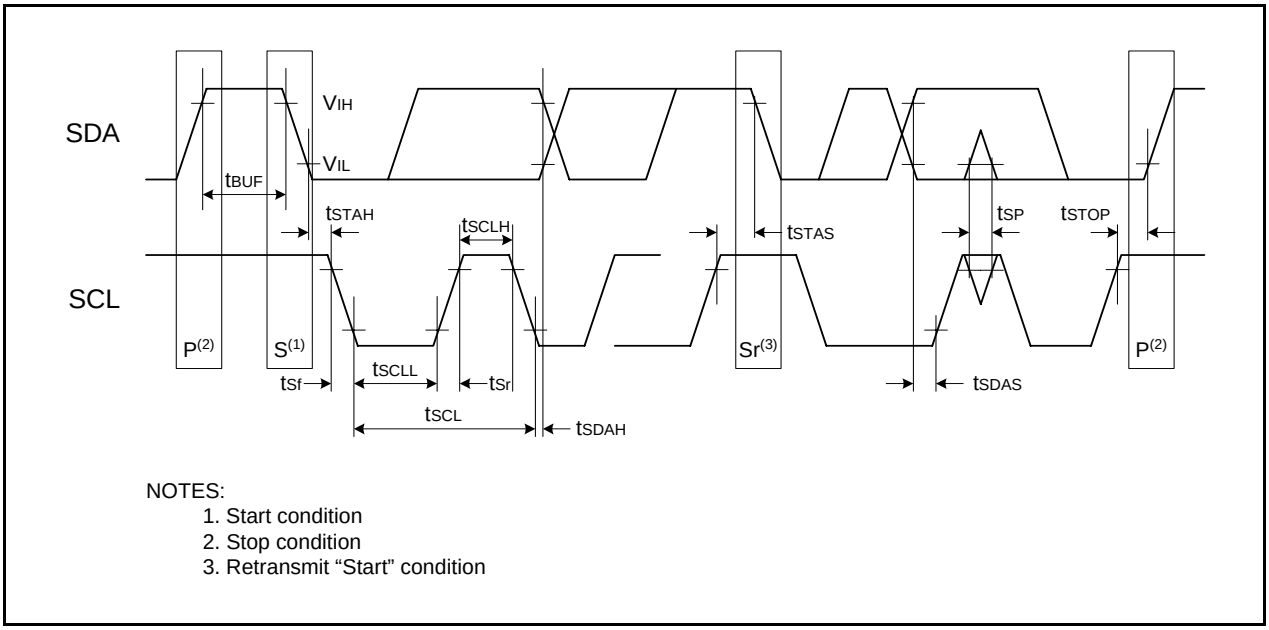
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for internal power supply stabilization during power-on(2)		1	–	2000	µs
$t_{d(R-S)}$	STOP exit time(3)		–	–	150	µs

NOTES:
1. The measurement condition is V_{CC} = 2.7 to 5.5 V and Topr = -40°C to 85°C (J version) / -40°C to 125°C (K version), unless otherwise specified.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.
3. Time until CPU clock supply starts since the interrupt is acknowledged to exit stop mode.

Table 5.13 Timing Requirements of I²C Bus Interface(1)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
t_{SCL}	SCL input cycle time		$12t_{CYC}$ + 600(2)	–	–	ns
t_{SCLH}	SCL input “H” width		$3t_{CYC}$ + 300(2)	–	–	ns
t_{SCLL}	SCL input “L” width		$5t_{CYC}$ + 300(2)	–	–	ns
t_{sf}	SCL, SDA input falling time		–	–	300	ns
t_{SP}	SCL, SDA input spike pulse rejection time		–	–	$1t_{CYC}$(2)	ns
t_{BUF}	SDA input bus-free time		$5t_{CYC}$(2)	–	–	ns
t_{STAH}	Start condition input hole time		$3t_{CYC}$(2)	–	–	ns
t_{STAS}	Retransmit start condition input setup time		$3t_{CYC}$(2)	–	–	ns
t_{STOP}	Stop condition input setup time		$3t_{CYC}$(2)	–	–	ns
t_{SOAS}	Data input setup time		$1t_{CYC}$ + 20(2)	–	–	ns
t_{SDAH}	Data input hold time		0	–	–	ns

NOTES:
1. V_{CC} = 2.7 to 5.5 V, V_{SS} = 0V at Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.
2. $1t_{CYC}$ = 1/f1(s)



NOTES:
1. Start condition
2. Stop condition
3. Retransmit “Start” condition

Figure 5.7 I/O Timing of I²C Bus Interface

Table 5.14 Electrical Characteristics (1) [Vcc = 5 V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output “H” Voltage	Except XOUT	I_{OH} = -5 mA		V_{CC} – 2.0	–	V_{CC}	V
			I_{OH} = -200 μA		V_{CC} – 0.3	–	V_{CC}	V
		XOUT	Drive capacity HIGH	I_{OH} = -1 mA	V_{CC} – 2.0	–	V_{CC}	V
			Drive capacity LOW	I_{OH} = -500 μA	V_{CC} – 2.0	–	V_{CC}	V
V_{OL}	Output “L” Voltage	Except XOUT	I_{OL} = 5 mA		–	–	2.0	V
			I_{OL} = 200 μA		–	–	0.45	V
		XOUT	Drive capacity HIGH	I_{OL} = 1 mA	–	–	2.0	V
			Drive capacity LOW	I_{OL} = 500 μA	–	–	2.0	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, TRAIO, RXD0, RXD1, CLK0, SSI, SCL, SDA, SSO			0.1	0.5	–	V
		$\overline{RESET}$			0.1	1.0	–	V
I_{IH}	Input “H” current		VI = 5 V, V_{CC} = 5 V		–	–	5.0	μA
I_{IL}	Input “L” current		VI = 0 V, V_{CC} = 5 V		–	–	-5.0	μA
R_{PULLUP}	Pull-Up Resistance		VI = 0 V, V_{CC} = 5 V		30	50	167	kΩ
R_{fXIN}	Feedback Resistance	XIN			–	1.0	–	MΩ
V_{RAM}	RAM Hold Voltage		During stop mode		2.0	–	–	V

NOTE:
1. V_{CC} = 4.2 to 5.5 V at Topr = -40 to 85°C (J version) / -40 to 125°C (K version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.15 Electrical Characteristics (2) [Vcc = 5 V]
(Topr = -40 to 85°C (J version) / -40 to 125°C (K version), Unless Otherwise Specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 3.3 to 5.5 V) In single-chip mode, the output pins are open and other pins are Vss	High-clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	11.0	22.0	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	8.8	17.6	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5.8	–	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	5.0	–	mA
			XIN = 16MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.8	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.8	–	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	5.8	11.6	mA
			XIN clock off High-speed on-chip oscillator on fOCO= 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.5	–	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8 FMR47 = 1	–	143	286	µA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA20 = 0 VCA26 = VCA27 = 0	–	53	106	µA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA20 = 0 VCA26 = VCA27 = 0	–	38	76	µA
		Stop mode Topr = 25°C	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	0.8	3.0	µA
		Stop mode Topr = 85°C	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	1.2	–	µA
		Stop mode Topr = 125°C	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	4.0	–	µA

Table 5.18 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLK0 input cycle time	200	–	ns
$t_{W(CKH)}$	CLK0 input “H” width	100	–	ns
$t_{W(CKL)}$	CLK0 input “L” width	100	–	ns
$t_{d(C-Q)}$	TXDi output delay time	–	50	ns
$t_{h(C-Q)}$	TXDi hold time	0	–	ns
$t_{su(D-C)}$	RXDi input setup time	50	–	ns
$t_{h(C-D)}$	RXDi input hold time	90	–	ns

i = 0 or 1

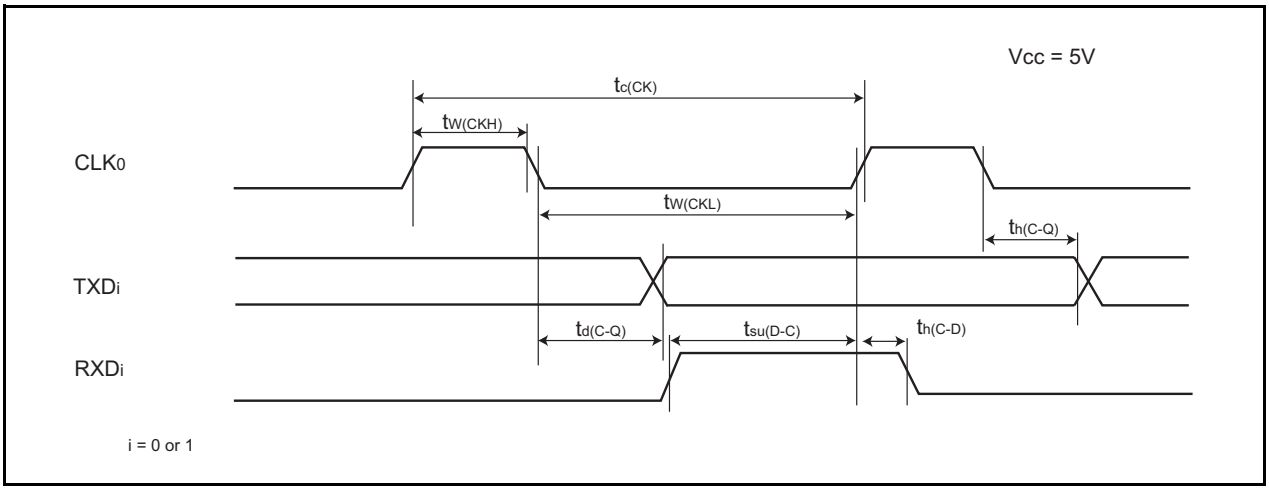


Figure 5.10 Serial Interface Timing Diagram when Vcc = 5 V

Table 5.19 External Interrupt $\overline{INTi}$ (i = 0 to 3) Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{W(INH)}$	$\overline{INTi}$ input “H” width	250(1)	–	ns
$t_{W(INL)}$	$\overline{INTi}$ input “L” width	250(2)	–	ns

NOTES:
1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use the $\overline{INTi}$ input HIGH width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use the $\overline{INTi}$ input LOW width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.

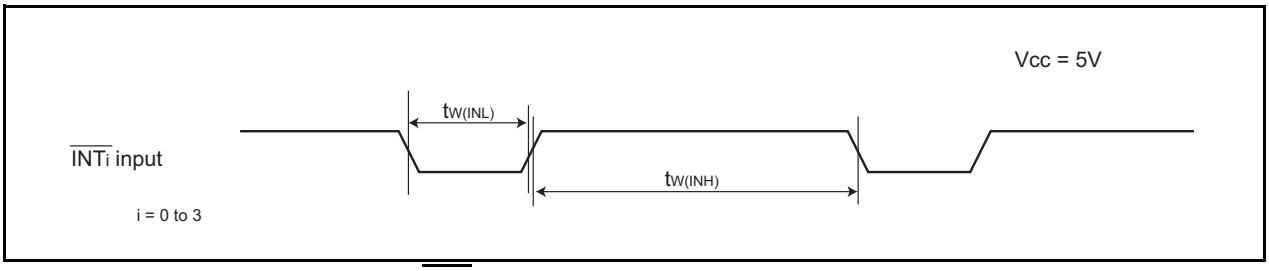


Figure 5.11 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 5 V (i = 0 to 3)

Table 5.24 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLK0 input cycle time	300	–	ns
$t_{W(CKH)}$	CLK0 input “H” width	150	–	ns
$t_{W(CKL)}$	CLK0 input “L” width	150	–	ns
$t_{d(C-Q)}$	TXDi output delay time	–	80	ns
$t_{h(C-Q)}$	TXDi hold time	0	–	ns
$t_{su(D-C)}$	RXDi input setup time	70	–	ns
$t_{h(C-D)}$	RXDi input hold time	90	–	ns

i = 0 or 1

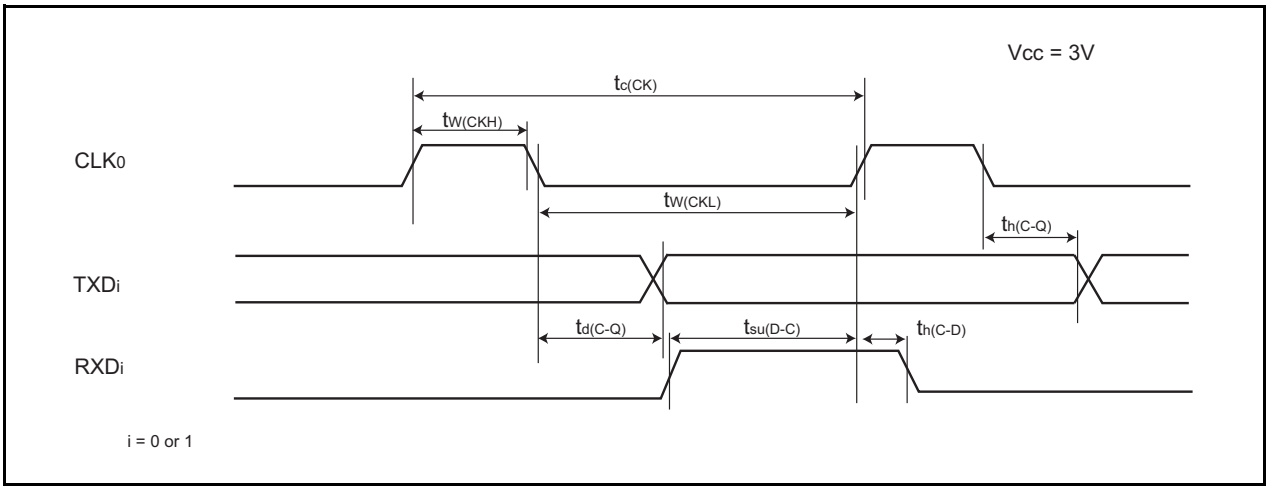


Figure 5.14 Serial Interface Timing Diagram when Vcc = 3 V

Table 5.25 External Interrupt $\overline{INTi}$ (i = 0 to 3) Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{W(INH)}$	$\overline{INTi}$ input “H” width	380(1)	–	ns
$t_{W(INL)}$	$\overline{INTi}$ input “L” width	380(2)	–	ns

NOTES:
1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use the $\overline{INTi}$ input HIGH width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use the $\overline{INTi}$ input LOW width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.

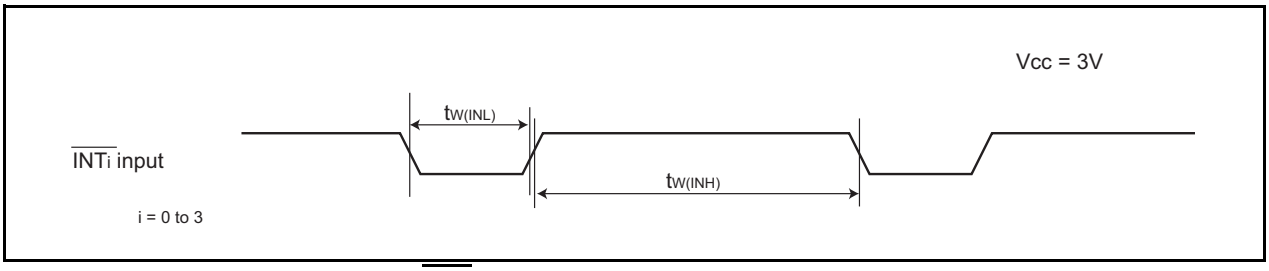
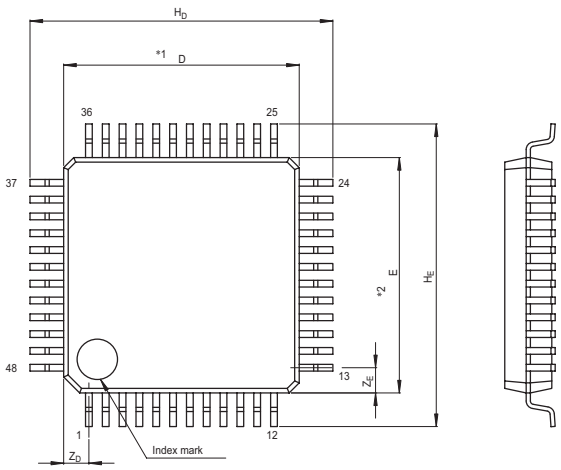


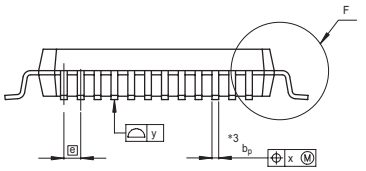
Figure 5.15 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 3 V (i = 0 to 3)

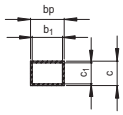
Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Technology website.

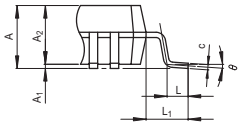
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP48-7x7-0.50	PLQP0048KB-A	48P6Q-A	0.2g







Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.9	7.0	7.1
E	6.9	7.0	7.1
A_2	—	1.4	—
H_D	8.8	9.0	9.2
H_E	8.8	9.0	9.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.17	0.22	0.27
b_1	—	0.20	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.10
Z_D	—	0.75	—
Z_E	—	0.75	—
L	0.35	0.5	0.65
L_1	—	1.0	—

REVISION HISTORY	R8C/20 Group, R8C/21 Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.10	Mar 08, 2005	–	First Edition issued
0.20	Sep 29, 2005	–	Words standardized - Clock synchronous serial interface → Clock synchronous serial I/O - Chip-select clock synchronous interface(SSU) → Clock synchronous serial I/O with chip select - I^2C bus interface(IIC) → I^2C bus interface
		2, 3	Table1.1 R8C/20 Group Performance, Table1.2 R8C/21 Group Performance Serial Interface revised: - Clock Synchronous Serial Interface: 1 channel I^2C bus Interface (3), Clock synchronous serial I/O with chip select - Power-On Reset Circuit added - Power Consumption value determined
		5, 6	Table 1.3 Product Information of R8C/20 Group, Table 1.4 Product Information of R8C/21 Group Date revised.
		7	Figure 1.4 Pin Assignment Pin name revised: - P3_5/$\overline{\text{SSC}}$K(/SCL) → P3_5/ SCL/$\overline{\text{SSC}}$K - P3_4/$\overline{\text{SCS}}$(/SDA) → P3_4/ SDA /$\overline{\text{SCS}}$ - VSS → VSS/AVSS - VCC → VCC/AVCC - P1_5/$\overline{\text{RXD0}}$/(TRAIO/$\overline{\text{INT1}}$) → P1_5/$\overline{\text{RXD0}}$/(TRAIO)/($\overline{\text{INT1}}$) - P6_6/$\overline{\text{INT2}}$/(TXD1) → P6_6/$\overline{\text{INT2}}$/TXD1 - P6_7/$\overline{\text{INT3}}$/(RXD1) → P6_7/$\overline{\text{INT3}}$/RXD1 - NOTE2 added
		8	Table 1.5 Pin Description - Analog Power Supply Input: line added - I^2C Bus Interface (IIC) → I^2C Bus Interface - SSU → Clock Synchronous Serial I/O with Chip Select
		9	Table 1.6 Pin Name Information by Pin Number revised - Pin Number 1: (SCL) → SCL - Pin Number 2: (SDA) → SDA - Pin Number 9: VSS → VSS/AVSS - Pin Number 11: VCC → VCC/AVCC - Pin Number 26: (TXD1) → TXD1 - Pin Number 27: (RXD1) → RXD1
		15	Table 4.1 SFR Information (1) revised - 0013h: XXXXXX00b → 00h
		17	Table 4.3 SFR Information (3) revised - 00BCh: 0000X000b → 00h/0000X000b
		18	Table 4.4 SFR Information (4) revised - 00D6h: 00000XXXb → 00h - 00F5h: UART1 Function Select Register added
		19	Table 4.5 SFR Information (5) revised - 0104h: TRATR → TRA

REVISION HISTORY	R8C/20 Group, R8C/21 Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.20	Sep 29, 2005	20	Table 4.6 SFR Information (6) revised - 0145h: POCR0 → TRDPOCR0 - 0146h, 0147h: TRDCNT0 → TRD0 - 0148h, 0149h: GRA0 → TRDGRA0 - 014Ah, 014Bh: GRB0 → TRDGRB0 - 014Ch, 014Dh: GRC0 → TRDGRC0 - 014Eh, 014Fh: GRD0 → TRDGRD0 - 0155h: POCR1 -> TRDPOCR1 - 0156h, 0157h: TRDCNT1 → TRD1 - 0158h, 0159h: GRA1 → TRDGRA1 - 015Ah, 015Bh: GRB1 → TRDGRB1 - 015Ch, 015Dh: GRC1 → TRDGRC1 - 015Eh, 015Fh: GRD1 → TRDGRD1
		22	5. Electrical Characteristics added
1.00	Nov 15, 2006	All pages	“Preliminary” and “Under development” deleted
		2	Table 1.1 Functions and Specifications for R8C/20 Group revised. NOTE1 deleted.
		3	Table 1.2 Functions and Specifications for R8C/21 Group revised. NOTE1 deleted.
		5	Table 1.3 Product Information for R8C/20 Group; “R5F2120AJFP (D)”, “R5F2120CJFP (D)”, “R5F2120AKFP (D)”, “R5F2120CKFP (D)”, and NOTE added. Figure 1.2 Type Number, Memory Size, and Package of R8C/20 Group; “A: 96 KB” and “C: 128 KB” added.
		6	Table 1.4 Product Information for R8C/21 Group; “R5F2121AJFP (D)”, “R5F2121CJFP (D)”, “R5F2121AKFP (D)”, “R5F2121CKFP (D)”, and NOTE added. Figure 1.3 Type Number, Memory Size, and Package of R8C/21 Group; “A: 96 KB” and “C: 128 KB” added.
		13	Figure 3.1 Memory Map of R8C/20 Group revised.
		14	Figure 3.2 Memory Map of R8C/21 Group revised.
		15	Table 4.1 SFR Information (1)(1); NOTE8; “The CSPROINI bit in the OFS register is set to 0.” → “The CSPROINI bit in the OFS register is 0.” revised.
		21	Table 5.1 Absolute Maximum Ratings; Power dissipation revised. Table 5.2 Recommended Operating Conditions; System clock revised.
		26	Table 5.8 Voltage Monitor 1 Reset Circuit Electrical Characteristics → Table 5.8 Power-on Reset Circuit, Voltage Monitor 1 Reset Circuit Electrical Characteristics(1) replaced. Table 5.8 revised. NOTE3 added. Table 5.9 Power-on Reset Circuit Electrical Characteristics deleted. Figure 5.3 Power-on Reset Circuit Electrical Characteristics revised.
		27	Table 5.10 High-Speed On-Chip Oscillator Circuit Electrical Characteristics → Table 5.9 High-Speed On-Chip Oscillator Circuit Electrical Characteristics revised.

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Colophon .7.2